RELIABILITY AND TEST CONDITIONS

Customized Component (SWA Series)

Items	Requirements	Test Methods and Remarks
1. Adhesive strength	① No visible mechanical damage. ② Inductance change: Within ±5% ③ DCR change: Within ±10%	① Apply the tensile 30N force progressively on the width and height of winding respectively. The direction of each force is perpendicular to them and parallel to the plate ② Keep time: 30±3s
2. Thermal Shock	① No visible mechanical damage. ② Inductance change: Within ±5% ③ DCR change: Within ±10%	① Temperature and time: -25±3℃ for 30±3 min→85℃ for 30±3min ② Transforming interval: 5 minute ③ Tested cycle: 100 cycles ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring
3. Resistance to Low Temperature	① No visible mechanical damage. ② Inductance change: Within ±5% ③ DCR change: Within ±10%	① Temperature: -25±3℃ ② Duration: $96^{\pm4}$ hours ③ The chip shall be stabilized at normal condition for 1~2 hours before measuring
4. Resistance to High Temperature	① No visible mechanical damage. ② Inductance change: Within ±5% ③ DCR change: Within ±10%	① Temperature: 85±2℃ ② Duration: $96^{\pm4}$ hours ③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
5. Damp Heat	① No visible mechanical damage. ② Inductance change: Within ±5% ③ DCR change: Within ±10%	① Temperature: 60±2℃ ② Humidity: 90% to 95%RH ③ Duration: $96^{\pm4}$ hours ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring
6. Package Drop	① No visible mechanical damage. ② Inductance change: Within ±5% ③ DCR change: Within ±10%	① Put the production in the carton ② Free fall from 800mm in height ③ Each faces of carton fall one time
7. Solderability	75% or more of electrode area shall be coated by new solder.	① The test samples shall be dipped in flux, and then immersed in molten solder. ② Solder temperature: 320±5℃ ③ Duration: 5±1 sec. ④ Solder: Sn/3.0Ag/0.5Cu ⑤ Flux: 25% resin and 75% ethanol in weight ⑥ Immersion depth: all sides of mounting terminal shall be immersed
8. Resistance to Soldering Heat	① 75% or more of electrode area shall be coated by new solder.	① The test samples shall be dipped in flux, and then immersed in molten solder. ② Solder temperature: 320±5℃ ③ Duration: 5±1 sec. ④ Solder: Sn/3.0Ag/0.5Cu ⑤ Flux: 25% resin and 75% ethanol in weight ⑥ Immersion depth: all sides of mounting terminal shall be immersed

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